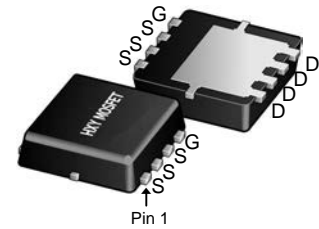


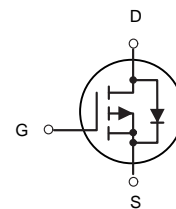


## Description

The HFTK3903Z uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



DFN3X3-8L



P-Channel MOSFET

## General Features

$V_{DS} = -30V$   $I_D = -55A$

$R_{DS(ON)} < 11m\Omega$  @  $V_{GS} = -10V$

## Application

Battery protection

Load switch

Uninterruptible power supply

## Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
HFTK3903Z	DFN3X3-8L	HXY MOSFET	5000

## Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-30	V
VGS	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	-55	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	-23	A
IDM	Pulsed Drain Current <sup>2</sup>	-140	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	78.8	mJ
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>4</sup>	21.5	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	5.8	$^\circ C/W$



**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> = -250μA	-30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V,	-	-	-1	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.0	-1.5	-2.5	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note3</small>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-12A	-	8.5	11	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A	-	13	18	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	2800	-	pF
C <sub>oss</sub>	Output Capacitance		-	346	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	319	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -15V, I <sub>D</sub> = -20A, V <sub>GS</sub> = -10V	-	30	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	5.3	-	nC
Q <sub>gd</sub>	Gate-Drain(“Miller”) Charge		-	7.6	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> = -15V, I <sub>D</sub> = -20A, V <sub>GS</sub> =-10V, R <sub>GEN</sub> =2.5Ω	-	14	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	20	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	95	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	65	-	ns
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	-55	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-140	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = -35A	-	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

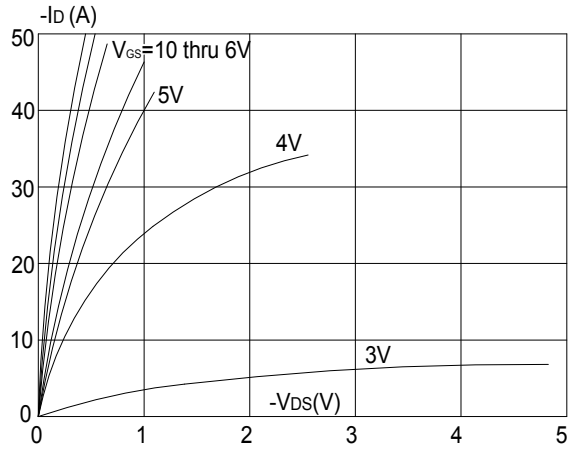
2. EAS condition:  $T_J=25^{\circ}\text{C}$ ,  $V_{DD}=-20V$ ,  $V_G=-10V$ ,  $L=0.5mH$ ,  $R_G=25\Omega$ ,  $I_{AS}=-17A$

3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 2\%$

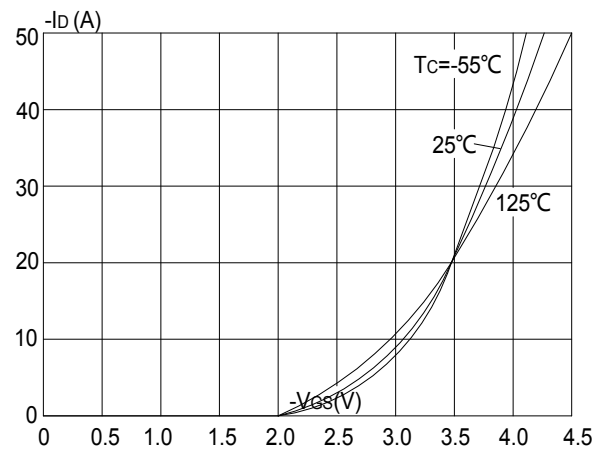


## Typical Performance Characteristics

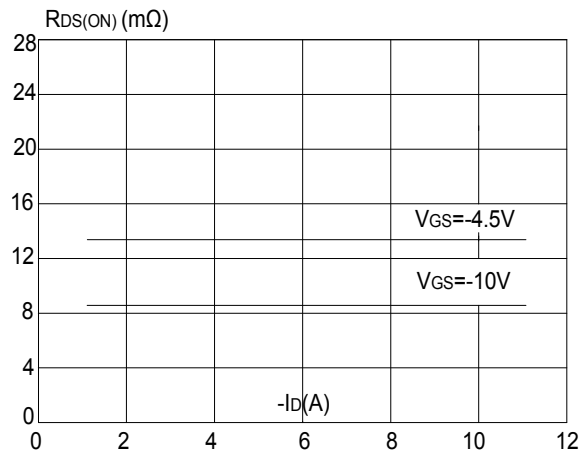
**Figure1: Output Characteristics**



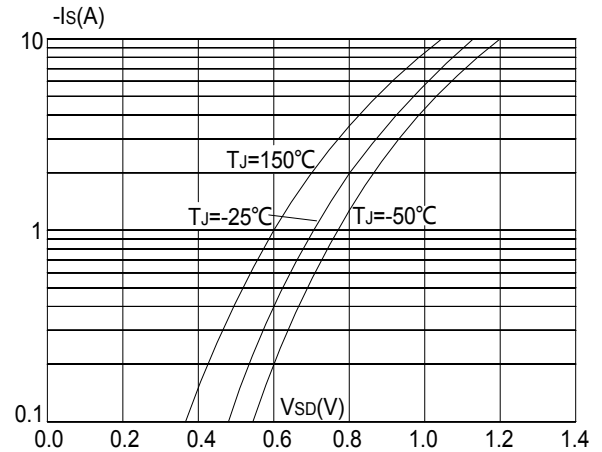
**Figure 2: Typical Transfer Characteristics**



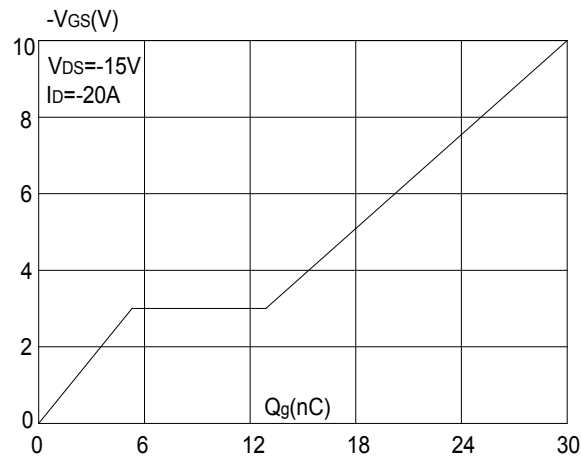
**Figure 3: On-resistance vs. Drain Current**



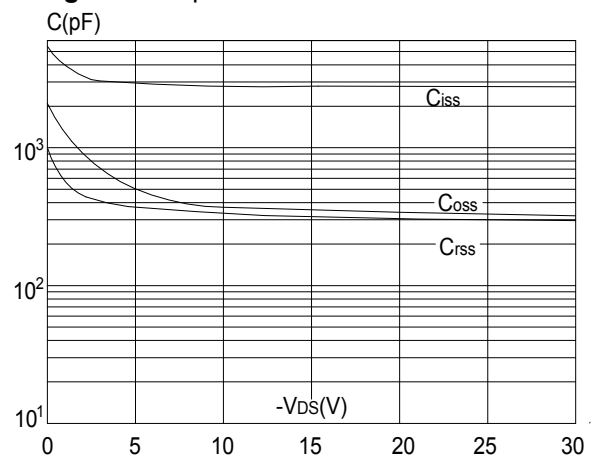
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

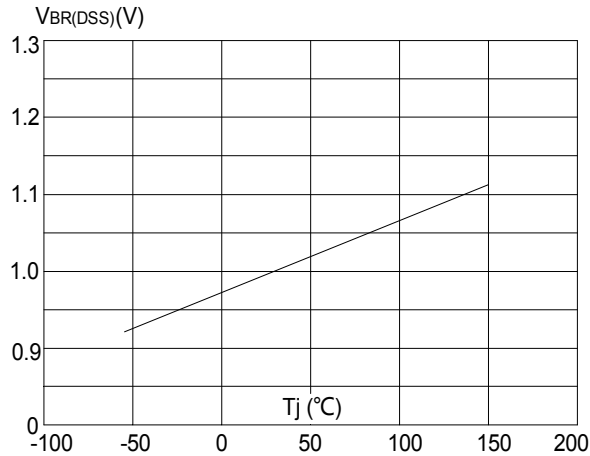


**Figure 6: Capacitance Characteristics**

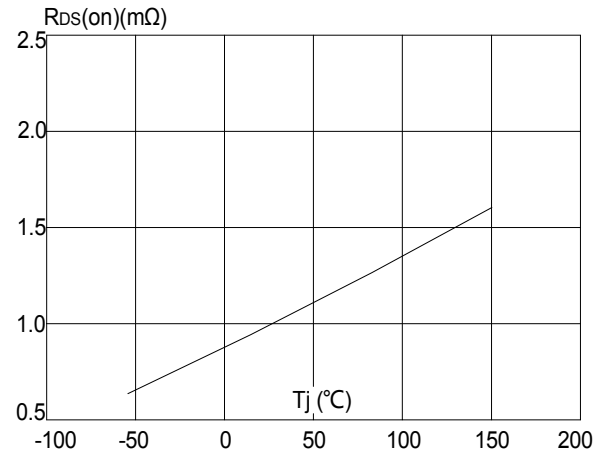




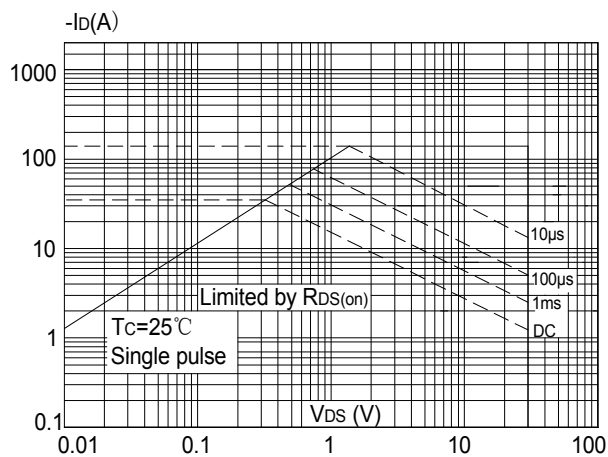
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



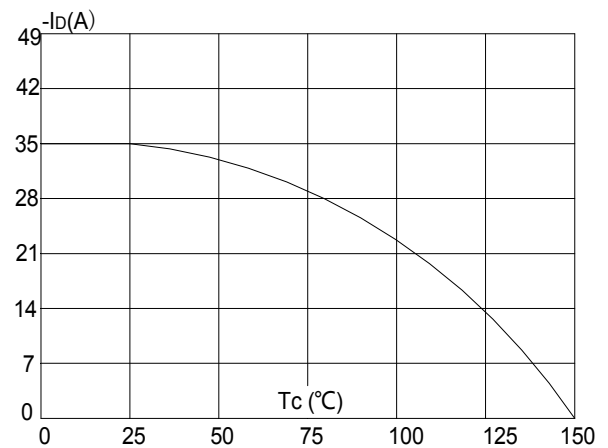
**Figure 8:** Normalized on Resistance vs. Junction Temperature



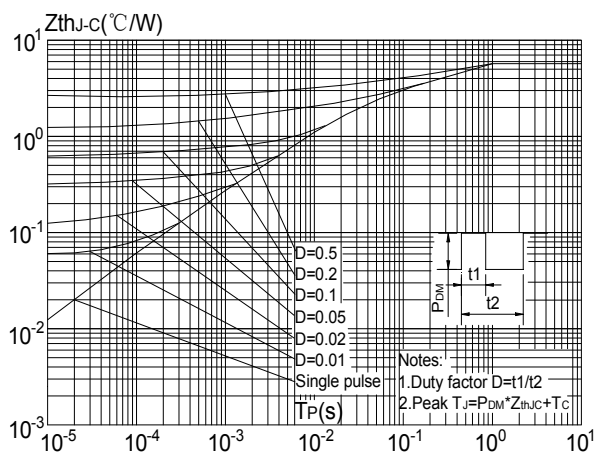
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

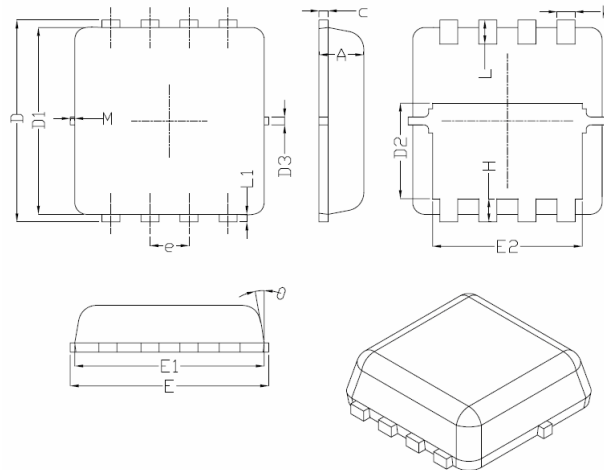


**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case





## DFN3X3-8L Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10°	12°



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